Electronic Pate	nt App	lication Fee	Transm	ittal			
Application Number:	105	10557694					
Filing Date:	22-	22-Nov-2005					
Title of Invention:		RESIN FOR PHOTORESIST COMPOSITION, PHOTORESIST COMPOSITION AND METHOD FOR FORMING RESIST PATTERN					
First Named Inventor/Applicant Name:	Hic	Hideo Hada					
Filer:	Nei	Neil S. Bartfeld/Jennifer Dolan					
Attorney Docket Number:	SHI	SHIGA7.033APC					
Filed as Large Entity	•						
U.S. National Stage under 35 USC 371 Fi	ling Fee	s					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Utility Appl issue fee		1501	1	1510	1510		

Publ. Fee- early, voluntary, or normal

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	10	3	30
	Tot	Total in USD (\$)		